

# **PacTech Flip Chip Solder Ball Placement and Laser Reflow System to be Demonstrated at SEMICON West**

Newly Enhanced Laser Solder Ball Bumping System with Repair and Rework Capability

Santa Clara, California—July 12, 2001—PacTech USA Packaging Technologies Inc, a leading supplier of services, equipment and processes for semiconductor wafer bumping, will be demonstrating the newly enhanced Laser Solder Ball Bumper at in booth 12024 during SEMICON West 2001.

The SB2-SM is a semiautomatic laser solder ball bumper capable singulate, position and to reflow 100µm – 760-µm solder balls of various alloys. The unique design of this system places no mechanical load on the device during ball placement and reflow. In addition a new automatic machine with a placement rate of up to 10 balls/sec is under development.

PacTech's Laser Solder Ball Bumper (SB2) has new features for repair/rework of solder balls on singulated chips or wafers. After installing the SB2 in many companies in Europe, Asia and the USA, PacTech today reports that it now offers a repair station capability as an option to existing SB2 systems already installed worldwide. New SB2 machines can be purchased with the repair station installed on the right side of the bond head. The SB2 uses the laser to reflow the balls and a vacuum system which extracts deformed solder balls.

The PacTech Laser Solder Ball Bumper is ideal for quick turn, fluxless, maskless bumping for Flip Chip, BGAs, CSPs, Modules, Optical Component attach or MEMs. With the repair station capability, the Laser Solder Ball Bumper (SB2) is clearly the most flexible machine out there with the least cost of ownership for R&D applications and with minor custom modification, production applications.

PacTech's SB2 is a non-substrate specific system, which translates to a high flexibility regarding different microelectronic devices. It can quickly be adapted to different or changed layouts of chips and wafers due to pad position programming. The relative short set-up time makes it ideal for production changes and lower over all cost to operate.

"In spite of the economic downturn," states Ron Blankenhorn, President of PacTech USA, "we are able to demonstrate saving associated with the state-of-the-art laser solder ball bumping technology for Flip Chip, Optic and MEM devices, and the SB2 system has already received world-wide acclaim."